

CLIPPEDIMAGE= JP404093052A

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TITLE: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

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INVENTOR-INFORMATION:

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NAME

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ABSTRACT:

PURPOSE: To prevent any crack from being produced and a wiring from being deformed and broken down by dispersing any stress applied to an IC chip, etc., to an outer frame ring by providing around the IC chip the outer frame ring with a thickness equal to or more of that of the IC chip.

CONSTITUTION: An IC chip 2 is bonded and fixed to an island 1, and each electrode of the IC chip 2 is electrically connected to each lead terminal 4 through a metal wire 3. An outer frame ring 6 has a thickness equal to or more of that of the IC chip 2 and is mounted on the island 1 or the lead terminal 4 through an adhesive. The outer frame ring 6 has a material

quality of an insulator with its insulator surface, and further has its melting point higher than that of a plastic molding part 5. The outer frame ring 6 is mounted in a range from the outer periphery of the IC chip 2 up to a connection port between the lead terminal 4 and the metal wire 3, and is located just under a loop of the metal wire 3. Hereby, the stress applied to the IC chip 2 can be dispersed, and a chip size is extended apparently to the outer frame ring 6 to prevent the IC chip 2 from being damaged.

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